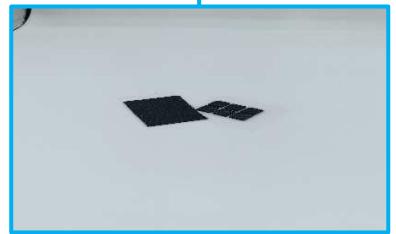


# Thermal Pad

Our Thermal Foams also called Gap Pad or Gap Filler are silicone-based thermo-conductive materials that help solve heat dissipation problems. The TEL\_150\_R is a specially developed mattress for applications where low cooling needs are required. Indeed, this is an excellent thermal conductor of 15W/ mK, with good thermal resistance facilitating heat transfer and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

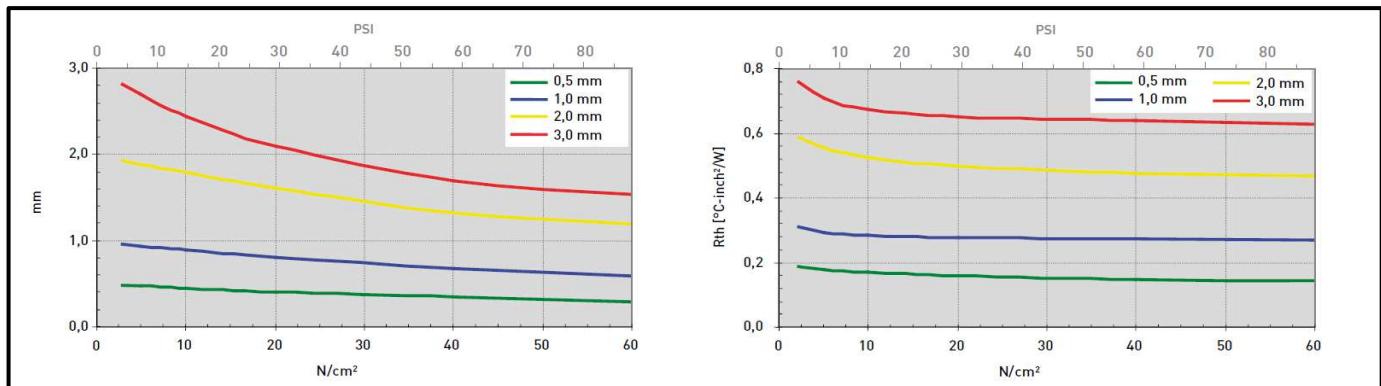


**Application areas:** Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

## Technical characteristics

Features	Unit	TEL_150_R			
<b>Thickness</b>	mm	0.5	1	2	-
<b>Reinforcement</b>	-		-		
<b>Color</b>	-		Black		
<b>Hardness</b>	Shore 00		55		
<b>Size</b>	mm	150*150	150*150	140*140	-
<b>Resistance @90 Psi</b>	°C-inch <sup>2</sup> /W (mm)	0.15 (0.30)	0.27 (0.60)	0.47 (1.20)	-
<b>Resistance @30 Psi</b>		0.16 (0.41)	0.28 (0.81)	0.50 (1.61)	-
<b>Resistance @10 Psi</b>		0.18 (0.47)	0.29 (0.93)	0.54 (1.85)	-
<b>Thermal conductivity</b>	W/mK		15		
<b>Temperature</b>	°C		-50 to 180		
<b>Breakdown voltage</b>	kV/mm		-		
<b>Volume resistance</b>	0hm - cm		$\geq 1 \times 10^{12}$		
<b>Contante dielectric</b>	@1MHz		-		

The TEL\_150\_R is available in 0.5/1/1.5/2/3mm thicknesses.



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.